

ABSTRACT

Provided is a heat-curable conductive paste composition having superior storage stability by preventing an increase in viscosity or a decrease in conductivity or due to storage, even if copper, a copper alloy, silver-coated copper that is copper coated with silver, or a coated copper alloy that is a copper alloy coated with silver is used as a conductive powder. The heat-curable conductive paste composition contains (A) a conductive powder, (B) a heat-curable resin, (C) a curing agent, and (D) an inorganic ion exchanger, wherein at least one member selected from the group consisting of copper, a copper alloy, silver-coated copper, and a silver-coated copper alloy is used as the conductive powder (A), and a blocked polyisocyanate compound, or a blocked polyisocyanate compound and an epoxy resin are contained as the heat-curable resin (B).